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# Contents

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<b>ACKNOWLEDGEMENTS</b> . . . . .	xi
<b>PREFACE</b> . . . . .	xiii
<b>PART 1. INFORMATION STORAGE AND THE STATE OF THE ART OF ELECTRONIC MEMORIES</b> . . . . .	1
<b>CHAPTER 1. GENERAL ISSUES RELATED TO DATA STORAGE AND ANALYSIS CLASSIFICATION OF MEMORIES AND RELATED PERSPECTIVES</b> . . . . .	3
1.1. Issues arising from the flow of digital information . . . . .	3
1.2. Current electronic memories and their classification . . . . .	5
1.3. Memories of the future. . . . .	8
<b>CHAPTER 2. STATE OF THE ART OF DRAM, SRAM, FLASH, HDD AND MRAM ELECTRONIC MEMORIES</b> . . . . .	13
2.1. DRAM volatile memories. . . . .	13
2.1.1. The operating principle of a MOSFET (metal oxide semiconductor field effect transistor) . . . . .	14
2.1.2. Operating characteristics of DRAM memories . . . . .	17
2.2. SRAM memories . . . . .	19
2.3. Non-volatile memories related to CMOS technology . . . . .	22

2.3.1. Operational characteristics of a floating gate MOSFET . . . . .	22
2.3.2. Flash memories. . . . .	38
2.4. Non-volatile magnetic memories (hard disk drives – HDDs and MRAMs) . . . . .	45
2.4.1. The discovery of giant magneto resistance at the origin of the spread of hard disk drives . . . . .	46
2.4.2. Spin valves . . . . .	49
2.4.3. Magnetic tunnel junctions . . . . .	51
2.4.4. Operational characteristics of a hard disk drive (HDD) . . . . .	51
2.4.5. Characteristics of a magnetic random access memory (MRAM) . . . . .	54
2.5. Conclusion. . . . .	56
<b>CHAPTER 3. EVOLUTION OF SSD TOWARD FERAM, FEFET, CTM AND STT-RAM MEMORIES . . . . .</b>	<b>59</b>
3.1. Evolution of DRAMs toward ferroelectric FeRAMs . . . . .	60
3.1.1. Characteristics of a ferroelectric material . . . . .	60
3.1.2. Principle of an FeRAM memory . . . . .	63
3.1.3. Characteristics of an FeFET memory. . . . .	67
3.2. The evolution of Flash memories towards charge trap memories (CTM) . . . . .	77
3.3. The evolution of magnetic memories (MRAM) toward spin torque transfer memories (STT-RAM) . . . . .	82
3.3.1. Nanomagnetism and experimental implications . . . . .	83
3.3.2. Characteristics of spin torque transfer . . . . .	84
3.3.3. Recent evolution with use of perpendicular magnetic anisotropic materials . . . . .	88
3.4. Conclusions . . . . .	90
<b>PART 2. THE EMERGENCE OF NEW CONCEPTS: THE INORGANIC NEMS, PCRAM, ReRAM AND ORGANIC MEMORIES . . . . .</b>	<b>93</b>
<b>CHAPTER 4. VOLATILE AND NON-VOLATILE MEMORIES BASED ON NEMS . . . . .</b>	<b>95</b>
4.1. Nanoelectromechanical switches with two electrodes . . . . .	96

4.1.1. NEMS with cantilevers . . . . .	97
4.1.2. NEMS with suspended bridge . . . . .	102
4.1.3. Crossed carbon nanotube networks . . . . .	103
4.2. NEMS switches with three electrodes . . . . .	106
4.2.1. Cantilever switch elaborated by lithographic techniques . . . . .	107
4.2.2. Nanoswitches with carbon nanotubes . . . . .	110
4.2.3. NEMS-FET hybrid memories with a mobile floating gate or mobile cantilever . . . . .	116
4.4. Conclusion . . . . .	121
<b>CHAPTER 5. NON-VOLATILE PHASE-CHANGE ELECTRONIC MEMORIES (PCRAM).</b> . . . . .	<b>123</b>
5.1. Operation of an electronic phase-change memory . . . . .	125
5.1.1. Composition and functioning of a GST PCRAM . . . . .	125
5.1.2. The antinomy between the high resistance of the amorphous state and rapid heating . . . . .	129
5.2. Comparison of physicochemical characteristics of a few phase-change materials. . . . .	134
5.3. Key factors for optimized performances of PCM memories . . . . .	137
5.3.1. Influence of cell geometry on the current $I_m$ needed for crystal melting. . . . .	138
5.3.2. Optimization of phase-change alloy composition to improve performance . . . . .	143
5.3.3. Influence of nanostructuration of the phase-change material . . . . .	148
5.3.4. Recent techniques for improvement of amorphization and crystallization rates of phase-change materials . . . . .	156
5.3.5. Problems related to interconnection of PCRAM cells in a 3D crossbar-type architecture . . . . .	160
5.4. Conclusion . . . . .	162
<b>CHAPTER 6. RESISTIVE MEMORY SYSTEMS (RRAM)</b> . . . . .	<b>165</b>
6.1. Main characteristics of resistive memories . . . . .	168
6.1.1. Unipolar system . . . . .	169

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6.1.2. Bipolar system . . . . .	170
6.2. Electrochemical metallization memories . . . . .	171
6.2.1. Atomic switches . . . . .	174
6.2.2. Metallization memories with an insulator or a semiconductor. . . . .	177
6.2.3. Conclusions on metallization memories . . . . .	182
6.3. Resistive valence change memories (VCM) . . . . .	183
6.3.1. The first work on resistive memories . . . . .	183
6.3.2. Resistive valence change memories after the 2000s . . . . .	185
6.3.3. A perovskite resistive memory (SrZrO <sub>3</sub> ) with better performance than Flash memories . . . . .	186
6.3.4. Electroforming and resistive switching. . . . .	189
6.3.5. Hafnium oxide for universal resistive memories? . . . . .	195
6.4. Conclusion. . . . .	198
<b>CHAPTER 7. ORGANIC AND NON-VOLATILE ELECTRONIC MEMORIES. . . . .</b>	<b>201</b>
7.1. Flash-type organic memories . . . . .	204
7.1.1. Flexible FG-OFET device with metal floating gate. . . . .	205
7.1.2. Flexible organic FG-OFET entirely elaborated by spin coating and inkjet printing . . . . .	212
7.1.3. Flexible OFETs with charge-trap gate dielectrics . . . . .	216
7.1.4. OFETs with conductive nanoparticles encapsulated in the gate dielectric . . . . .	221
7.1.5. Redox dielectric OFETs . . . . .	226
7.2. Resistive organic memories with two contacts. . . . .	230
7.2.1. Organic memories based on electrochemical metallization . . . . .	232
7.2.2. Resistive charge-trap organic memories . . . . .	238
7.3. Molecular memories . . . . .	244
7.4. Conclusion. . . . .	248

<b>CONCLUSION</b> . . . . .	251
<b>BIBLIOGRAPHY</b> . . . . .	255
<b>INDEX</b> . . . . .	285